

### [ECX-2210MXA \(I210\)](#)



10th Gen Intel® Xeon®/Core™ i9/i7/i5/i3 Processor (Comet Lake) with Workstation-grade Intel® W480E Chipset Expandable Fanless Embedded Workstation, 6 GigE LAN with 4 M12 PoE+, 2 front-access SSD trays, 1 PCIe x16 slot, 3 Nano SIM, 6 USB 3.2, 4 COM RS-232/422/485, M.2 Key B, M.2 Key E, M.2 Key M, 32 Isolated DIO, High-Performance, Rugged, Extended Temperature

### [ECX-2201MXA \(I210\)](#)



10th Gen Intel® Xeon®/Core™ i9/i7/i5/i3 Processor (Comet Lake) with Workstation-grade Intel® W480E Chipset Expandable Fanless Embedded Workstation, 6 GigE LAN with 4 M12 PoE+, 2 front-access SSD trays, 1 PCI slot, 3 Nano SIM, 6 USB 3.2, 4 COM RS-232/422/485, M.2 Key B, M.2 Key E, M.2 Key M, 32 Isolated DIO, High-Performance, Rugged, Extended Temperature

## [ECX-2210A \(I210\)](#)



10th Gen Intel® Xeon®/Core™ i9/i7/i5/i3 Processor (Comet Lake) with Workstation-grade Intel® W480E Chipset Expandable Fanless Embedded Workstation, 6 GigE LAN with 4 PoE+, 2 front-access SSD trays, 1 PCIe x16 slot, 3 Nano SIM, 6 USB 3.2, 4 COM RS-232/422/485, M.2 Key B, M.2 Key E, 32 Isolated DIO, High-Performance, Rugged, Extended Temperature

## [ECX-2201A \(I210\)](#)



10th Gen Intel® Xeon®/Core™ i9/i7/i5/i3 Processor (Comet Lake) with Workstation-grade Intel® W480E Chipset Expandable Fanless Embedded Workstation, 6 GigE LAN with 4 PoE+, 2 front-access SSD trays, 1 PCI slot, 3 Nano SIM, 6 USB 3.2, 4 COM RS-232/422/485, M.2 Key B, M.2 Key E, M.2 Key M, 32 Isolated DIO, High-Performance, Rugged, Extended Temperature

## [ECX-2110A \(I210\)](#)



10th Gen Intel® Xeon®/Core™ i9/i7/i5/i3 Processor (Comet Lake) with Workstation-grade Intel® W480E Chipset Expandable Fanless Embedded Workstation, 2 GigE LAN, 2 front-access SSD trays, 1 PCIe x16, 3 Nano SIM, 6 USB 3.2, 4 COM RS-232/422/485, M.2 Key B, M.2 Key E, M.2 Key M, 16 GPIO, High-Performance, Rugged, Extended Temperature

## [ECX-2101A \(I210\)](#)



10th Gen Intel® Xeon®/Core™ i9/i7/i5/i3 Processor (Comet Lake) with Workstation-grade Intel® W480E Chipset Expandable Fanless Embedded Workstation, 2 GigE LAN, 2 front-access SSD trays, 1 PCI slot, 3 Nano SIM, 6 USB 3.2, 4 COM RS-232/422/485, M.2 Key B, M.2 Key E, M.2 Key M, 16 GPIO, High-Performance, Rugged, Extended Temperature

## [ECX-2210MX \(I350\)](#)



10th Gen Intel® Xeon®/Core™ i9/i7/i5/i3 Processor (Comet Lake) with Workstation-grade Intel® W480E Chipset Expandable Fanless Embedded Workstation, 6 GigE LAN with 4 M12 PoE+, 2 front-access SSD trays, 1 PCIe x16 slot, 3 Nano SIM, 6 USB 3.2, 4 COM RS-232/422/485, M.2 Key B, M.2 Key E, M.2 Key M, 32 Isolated DIO, High-Performance, Rugged, Extended Temperature

## [ECX-2201MX \(I350\)](#)



10th Gen Intel® Xeon®/Core™ i9/i7/i5/i3 Processor (Comet Lake) with Workstation-grade Intel® W480E Chipset Expandable Fanless Embedded Workstation, 6 GigE LAN with 4 M12 PoE+, 2 front-access SSD trays, 1 PCI slot, 3 Nano SIM, 6 USB 3.2, 4 COM RS-232/422/485, M.2 Key B, M.2 Key E, M.2 Key M, 32 Isolated DIO, High-Performance, Rugged, Extended Temperature

## [ECX-2210 \(I350\)](#)



10th Gen Intel® Xeon®/Core™ i9/i7/i5/i3 Processor (Comet Lake) with Workstation-grade Intel® W480E Chipset Expandable Fanless Embedded Workstation, 6 GigE LAN with 4 PoE+, 2 front-access SSD trays, 1 PCIe x16 slot, 3 Nano SIM, 6 USB 3.2, 4 COM RS-232/422/485, M.2 Key B, M.2 Key E, 32 Isolated DIO, High-Performance, Rugged, Extended Temperature

## [ECX-2201 \(I350\)](#)



10th Gen Intel® Xeon®/Core™ i9/i7/i5/i3 Processor (Comet Lake) with Workstation-grade Intel® W480E Chipset Expandable Fanless Embedded Workstation, 6 GigE LAN with 4 PoE+, 2 front-access SSD trays, 1 PCI slot, 3 Nano SIM, 6 USB 3.2, 4 COM RS-232/422/485, M.2 Key B, M.2 Key E, M.2 Key M, 32 Isolated DIO, High-Performance, Rugged, Extended Temperature